

L Number	Hits	Search Text	DB	Time stamp
1	27	438/689.ccls. and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:40
2	20789	wafer near (remov\$3 or thin\$4 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:59
3	6724	(wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:07
4	4257	(wafer near (remov\$3 or thin\$4 or etch\$3)) and ((glass or holder) with (wafer or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:08
5	2407	((wafer near (remov\$3 or thin\$4 or etch\$3)) and ((glass or holder) with (wafer or silicon))) and (via or trench or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:10
6	342	((wafer near (remov\$3 or thin\$4 or etch\$3)) and ((glass or holder) with (wafer or silicon))) and (via or trench or cavity)) and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:59
7	8198	(wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder or chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:07
8	5782	((wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder or chuck)) and ((glass or holder or chuck) with (wafer or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:08
9	3184	((wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder or chuck)) and ((glass or holder or chuck) with (wafer or silicon))) and (via or trench or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:10
10	477	((wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder or chuck)) and ((glass or holder or chuck) with (wafer or silicon))) and (via or trench or cavity)) and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 11:11
11	392	((wafer near (remov\$3 or thin\$4 or etch\$3)) and (glass or holder or chuck)) and ((glass or holder or chuck) with (wafer or silicon))) and (via or trench or cavity)) and ball\$2) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:06

12	92	("3739463" "3810129" "3811117" "3838501" "3881884" "3991296" "3993917" "4139401" "4141135" "4368106" "4394712" "4463336" "4467518" "4603341" "4612083" "4628174" "4722130" "4729971" "4769738" "4807021" "4822755" "4842699" "4897708" "4954458" "4978639" "4996587" "5024970" "5064771" "5071792" "5135878" "5160987" "5166097" "5191405" "5225771" "5259924" "5268326" "5270261" "5307942" "5309318" "5313097" "5314844" "5322816" "5323035" "5340771" "5380681" "5399898" "5414637" "5426566" "5453404" "5463246" "5466634" "5467305" "5468663" "5472914" "5478781" "5489554" "5494832" "5502333" "5502667" "5504036" "5506753" "5517057" "5517754" "5532519" "5550942" "5561622" "5563086" "5567653" "5567654" "5571754" "5596226" "5627106" "5646067" "5654127" "5656553" "5691248" "5707485" "5766984" "5824595" "5843844" "5846879" "5851845" "5888882" "5888883" "5979475" "5998292" "6004867" "6083811" "6121119" "6162701" "6176966" "6184060").PN.	USPAT	2003/01/15 11:28
13	5	("5024970" "5223450" "5270261" "5346848" "5691248").PN.	USPAT	2003/01/15 11:32
14	13	6004867.URPN.	USPAT	2003/01/15 11:32
15	4	("3508980" "4839309" "5013681" "5091330").PN.	USPAT	2003/01/15 11:37
18	41	5071792.URPN.	USPAT	2003/01/15 11:40
19	11	5903044.URPN.	USPAT	2003/01/15 11:59
21	336		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:39
22	712	(wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch) or beol)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:38
23	668	(wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:39
24	593	((wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch))) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:52
25	490	((wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch))) and (@ad<20010531)) and (chip or die or package or ball\$2 or via or trench or groove or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:50
26	0	(wafer near ball\$2) and ((trench or groove or cavity) near wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:52

27	109	(wafer near ball\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:52
28	92	((wafer near ball\$2)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 12:59
29	135	438/For.403.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:04
30	135	438/For.403.ccls. and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:05
31	13	438/For.403.ccls. and (ball\$s or contact or interconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:04
32	468	438/977.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:04
33	319	438/977.ccls. and (ball\$s or contact or interconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:04
34	314	(438/977.ccls. and (ball\$s or contact or interconnect\$3)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 13:05